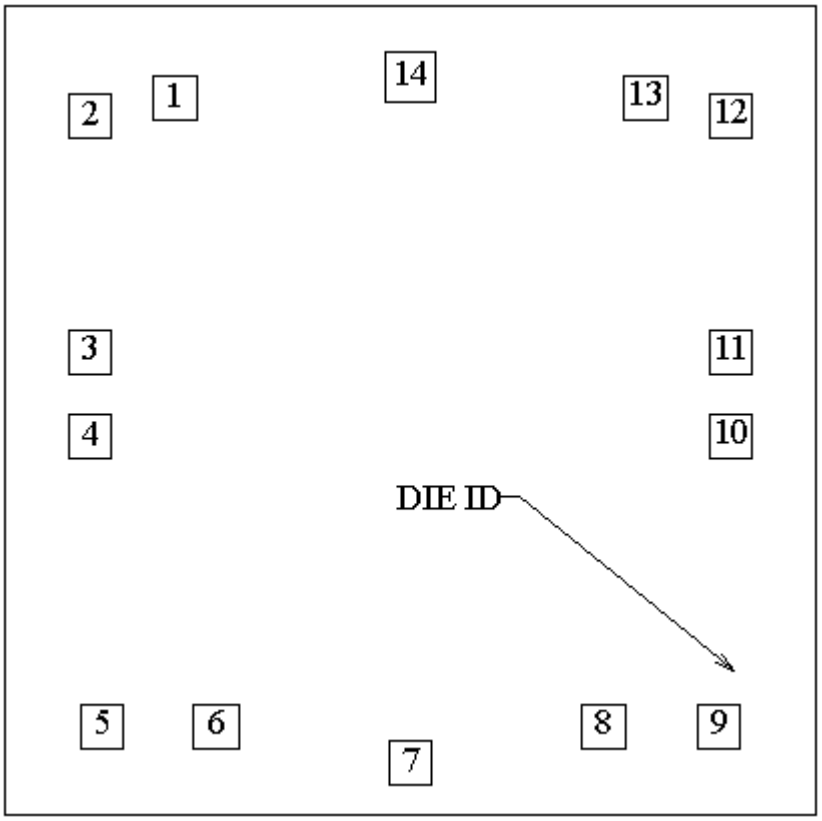
LM556 MD8 MW8
DUAL TIMER

March 28,2007

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	556A	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1702µm x 1702µm 67.0mils x 67.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	177µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
DISCHARGE	1	-495	656	91	x	91
THRESHOLD	2	-673	618	91	x	91
CONT VOLT	3	-673	123	91	x	91
RESET	4	-673	-55	91	x	91
OUTPUT	5	-648	-665	91	x	91
TRIGGER	6	-408	-665	94	x	91
GND	7	0	-741	91	x	91
TRIGGER	8	406	-665	91	x	91
OUTPUT	9	648	-665	91	x	91
RESET	10	673	-55	91	x	91
CONT VOLT	11	673	123	91	x	91
THRESHOLD	12	673	618	91	x	91
DISCHARGE	13	495	656	91	x	91
VCC	14	0	700	102	x	104

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